For more information

Please visit
the official website
of DELEC.

www.delec.com.cn

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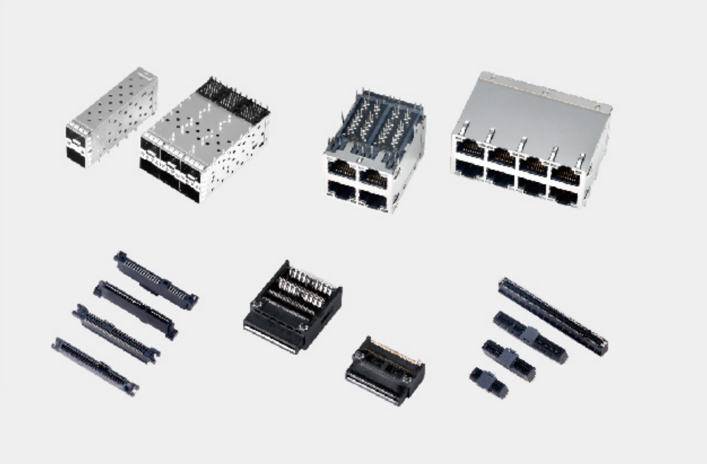
DELEC®
Connectors



东莞市多亚电子有限公司
Duoya Electronics Company Limited

PDF
ONLINE CATALOG

in Producing Connectors And Cables

Brief introduction

Established in December1997, DELEC is a rapidly expanding company in the telecommuni-cations and computer interconnector market. We produce a wide array of telecommunications jacks and computer connectors.

Quality is the core value in our company. We believe quality is thedriving force to our success and support from our partner. Being acertified ISO 9001:2004 company makes us vigilant and demanding on our products. With our ISO14001 in 2001, we take precaution in protecting the environment. All ofour product lines also meet UL and CUL safety standards.

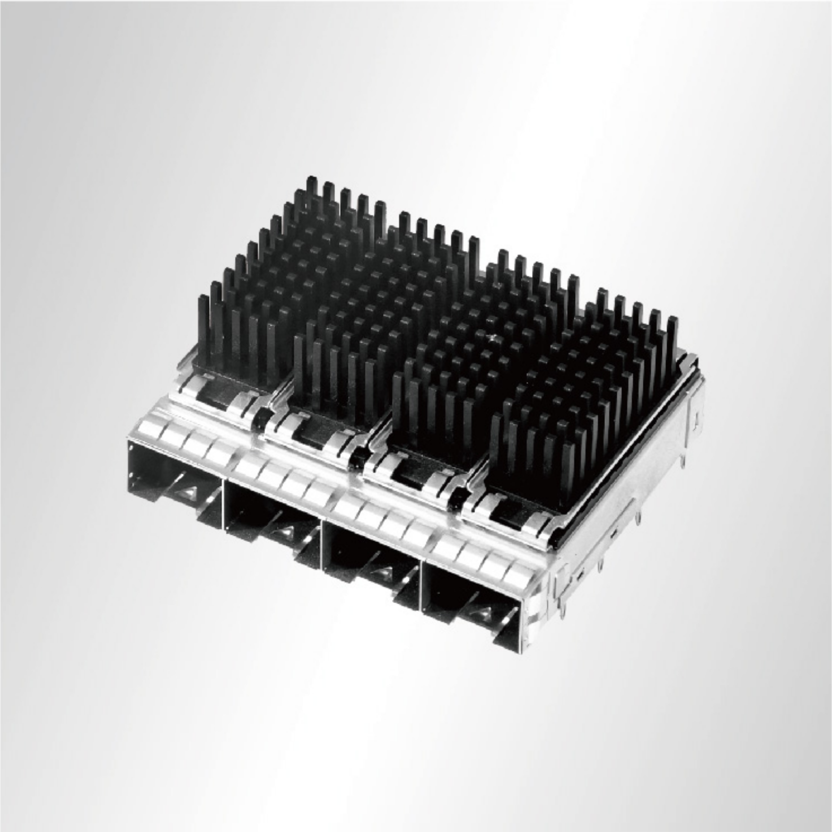
We have developed innovative designs for a variety os integrated network interface modules thatvary in application. Our latest series of interface modules include increase in density, reduction in modular components that deliver greater value to customers. Our design efforts on 10 baseT, 10/100 TX, Gigabit magnetic electronics components, and RJ-45 metal screen covers have been widely acceptedand are the industry standard.

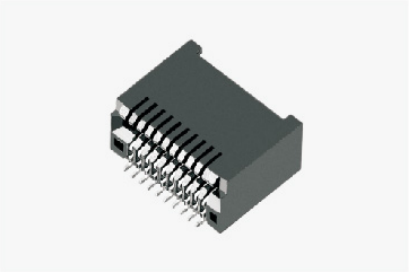
Our Goals

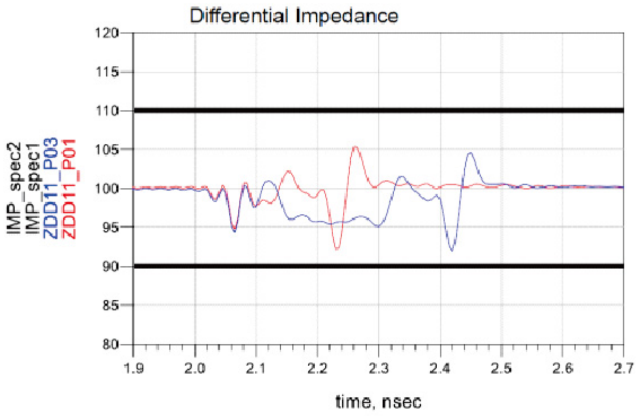
- 1) Continue to develop new andinnovative designs for all product offerings;
- 2) Maintain a people-oriented team with high integrity that will help to expand our company;
- 3) Provide excellent quality customer service and maintain long term relationships with our customer,
- 4) Provide improved customer service with future ERP and CRM support.

Quality Certification

Single & Rows SFP, SFP+, SFP28, SFP56







Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 20-position SFP connectors complying with MSA Agreement INF-8074i and SFF-8081 and SFF-8083 and SFF-8432 and SFF-8433.

Configurations(Rows x Ports per Row)

1. 1x1 1x2 1x4 1x6
2. 2x1 2x2 2x3 2x4 2x6 2x8 2x12

General Characteristics

1. Rohs Compliant
2. Industry Standard Footprint
3. Industry Standard EIA-364

Mechanical Characteristics

1.Compliant Press-Fit Pins or Solder Tails（Single Ports)
2.Durability:250 Mating Cycles min
Electrical Characteristics
1. Hot Swappable
2. Operating Voltage:3.3V
3. Operating Current:0.5A
4. Differential Impedance:100Ω+/-10Ω
5. DWV:300 V AC
6.Insulation Resistance:1000MΩmin
7.Contact Resistance:70mΩmax

Materials

1.Cage:Base Material: Copper Alloy
  Light Pipe: Optical Grade Polycarbonate
  Heat Sink: Aluminum Alloy
  Heat Sink Clip: Stainless Steel
  Dust Cover: Thermoplastic
  EMI Ground Tabs: Stainless Steel
2.Connector
  Contact Base Material: Copper Alloy
  Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
  Housings: Glass Reinforced, Lee-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

1. Operating Temperature:-40℃ to +85℃
2. Storage Temperature:-55℃ to +105℃

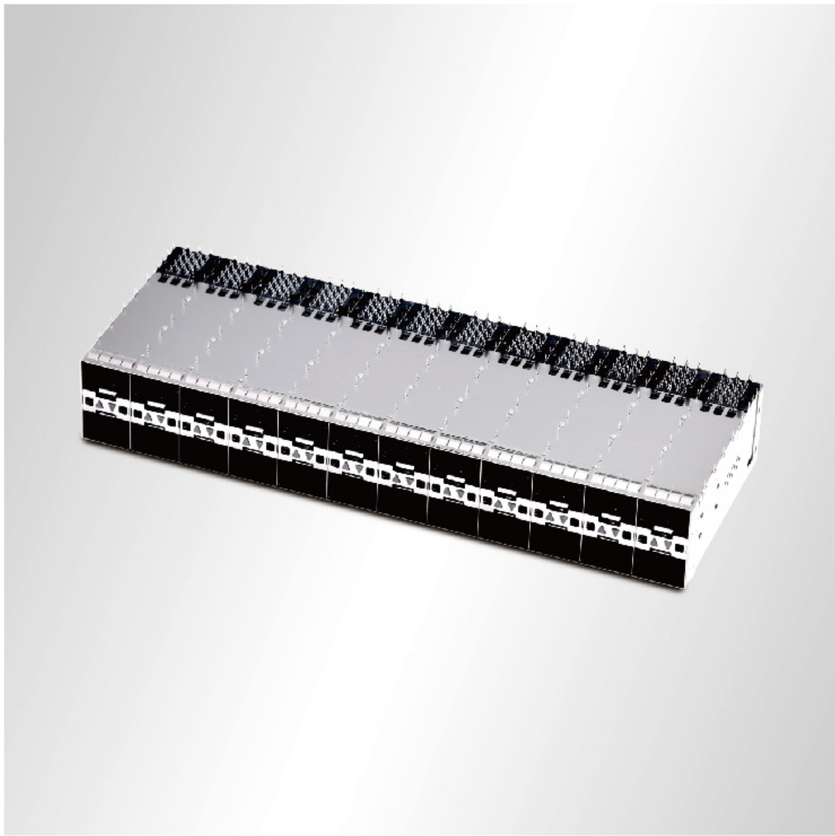
Options

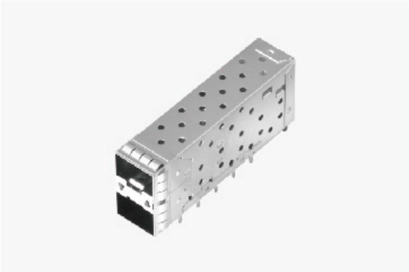
1.Dust Cover
2. Light Pipe(Inner Light Pipes or Outer Light Pipes)
3. Heat Sink
4. EMI Spring Fingers
   Metal Spring Fingers
   Conductive Elastomeric Gasket

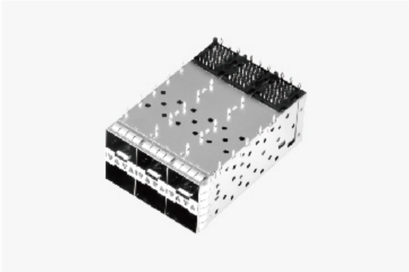
Packaging

1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover

Stacked SFP, SFP+, SFP28, SFP56







Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 20-position SFP connectors complying with MSA Agreement INF-8074i and SFF-8081 and SFF-8083 and SFF-8432 and SFF-8433.

Configurations(Rows x Ports per Row)

1. 1x1 1x2 1x4 1x6
2. 2x1 2x2 2x3 2x4 2x6 2x8 2x12

General Characteristics

1.Rohs Compliant
2.Industry Standard Footprint
3.Industry Standard EIA-364

Mechanical Characteristics

1.Compliant Press-Fit Pins or Solder Tails（Single Ports)
2.Durability:250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2.Operating Voltage: 3.3V
3.Operating Current: 0.5A
4.Differential Impedance: 100Ω+/-10Ω
5.DWV: 300 V AC
6.Insulation Resistance: 1000MΩmin
7.Contact Resistance: 70mΩmax

Materials

1.Cage:Base Material: Copper Alloy
  Light Pipe: Optical Grade Polycarbonate
  Heat Sink: Aluminum Alloy
  Heat Sink Clip: Stainless Steel
  Dust Cover: Thermoplastic
  EMI Ground Tabs: Stainless Steel
2.Connector
  Contact Base Material: Copper Alloy
  Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
  Housings: Glass Reinforced, Lee-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

1.Operating Temperature: -40℃ to +85℃
2.Storage Temperature: -55℃ to +105℃

Options

1.Dust Cover
2.Light Pipe(Inner Light Pipes or Outer Light Pipes)
3.Heat Sink
4.EMI Spring Fingers
   Metal Spring Fingers
   Conductive Elastomeric Gasket

Packaging

1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover

Single & Rows QSFP+ / QSFP28 / QSFP56 1×N Cage / Connector

Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 38-position QSFP connectors complying with MSA Agreement SFF-8682 and SFF-8672 and SFF-8683 and SFF-8662 and SFF-8663.

Configurations(Rows x Ports per Row)

1. 1x1 1x2 1x3 1x4General Characteristics
1.Rohs Compliant
2.Industry Standard Footprint
3.Industry Standard EIA-364

Mechanical Characteristics

1.Compliant Press-Fit Pins or Solder Tails（Single Ports)
2.Durability:250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2.Operating Voltage:30VDC per contact
3.Operating Current:0.5A
4.Differential Impedance:100Ω+/-10Ω
5.DWV:300 V AC
6.Insulation Resistance:1000MΩmin
7.Contact Resistance:70mΩmax

Materials

1.Cage:Base Material: Copper Alloy
  Light Pipe: Optical Grade Polycarbonate
  Heat Sink: Aluminum Alloy
  Heat Sink Clip: Stainless Steel
  Dust Cover: Thermoplastic
  EMI Ground Tabs: Stainless Steel
2.Connector
  Contact Base Material: Copper Alloy
  Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
  Housings: Glass Reinforced, Lee-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

1.Operating Temperature:-40℃ to +85℃
2.Storage Temperature:-55℃ to +105℃

Options

1.Dust Cover
2.Light Pipe(Inner Light Pipes or Outer Light Pipes)
3.Heat Sink
4.EMI Spring Fingers
  Metal Spring Fingers
  Conductive Elastomeric Gasket

Packaging

1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover

Single / Stacked QSFP+ / QSFP28 / QSFP56 2×N Connector

Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 38-position QSFP connectors complying with MSA Agreement SFF-8682 and SFF-8672 and SFF-8683 and SFF-8662 and SFF-8663.

Configurations(Rows x Ports per Row)

1. 2x1 2x2 2x3 2x4
General Characteristics
1.Rohs Compliant
2.Industry Standard Footprint
3.Industry Standard EIA-364
Mechanical Characteristics
1.Compliant Press-Fit Pins or Solder Tails（Single Ports)
2.Durability:250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2.Operating Voltage:30VDC per contact
3.Operating Current:0.5A
4.Differential Impedance:100Ω+/-10Ω
5.DWV:300 V AC
6.Insulation Resistance:1000MΩmin
7.Contact Resistance:70mΩmax

Materials

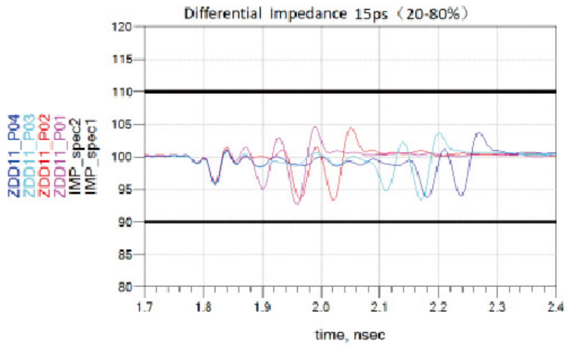
1.Cage:Base Material: Copper Alloy
  Light Pipe: Optical Grade Polycarbonate
  Heat Sink: Aluminum Alloy
  Heat Sink Clip: Stainless Steel
  Dust Cover: Thermoplastic
  EMI Ground Tabs: Stainless Steel
2.Connector
  Contact Base Material: Copper Alloy
  Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
  Housings: Glass Reinforced, Lee-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

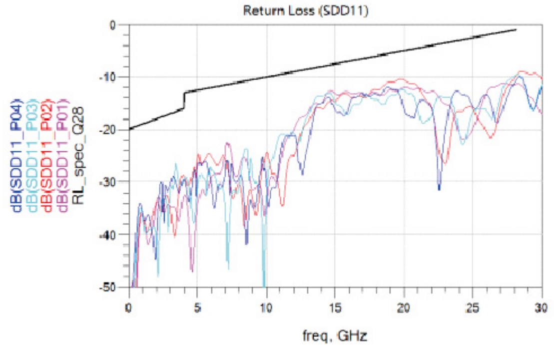
Temperature Rating

1.Operating Temperature:-40℃ to +85℃
2.Storage Temperature:-55℃ to +105℃
Options
1.Dust Cover
2.Light Pipe(Inner Light Pipes or Outer Light Pipes)
3.Heat Sink
4.EMI Spring Fingers
  Metal Spring Fingers
  Conductive Elastomeric Gasket

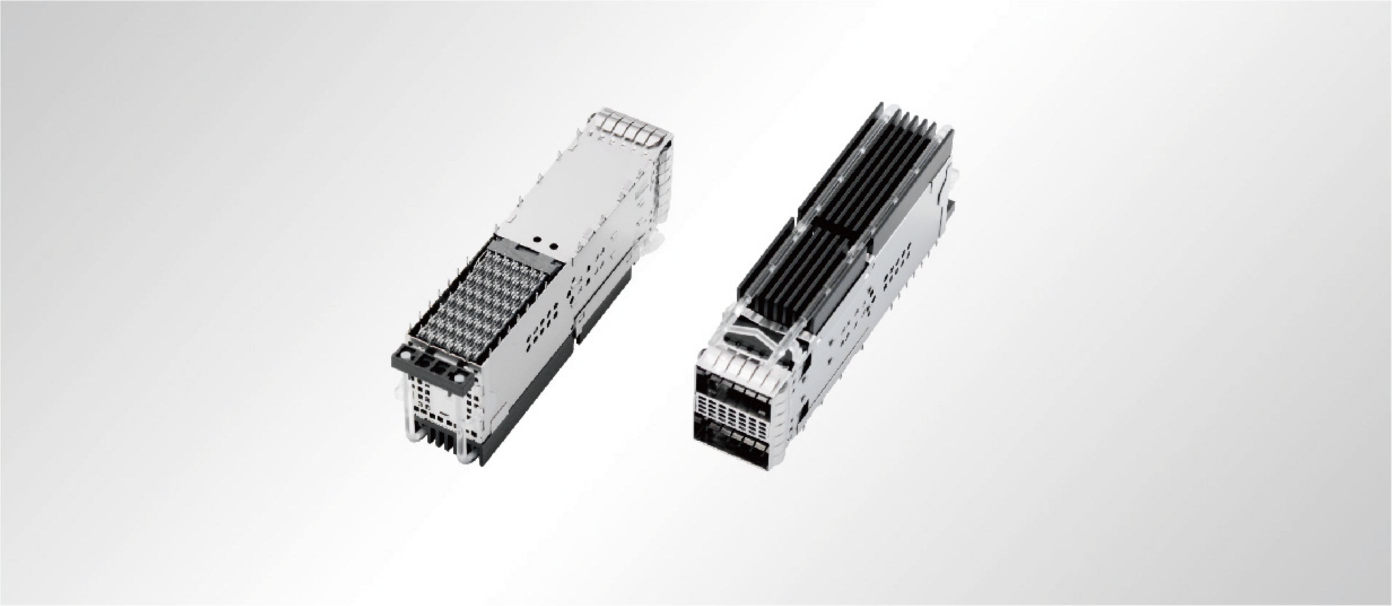
Packaging

1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover





Single & Stacked SFP-DD&QSFP-DD



Specification Highlights

complying with SFP-DD MSA Agreement and INF-8628

Configurations(Rows x Ports per Row)

1. 1x1 2. 2x1 General Characteristics
1.Rohs Compliant
2.Industry Standard Footprint
3.Industry Standard EIA-364

Mechanical Characteristics

1.Compliant Press-Fit Pins or Solder Tails (Single Ports)
2.Durability:250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2.Operating Voltage:30VDC per contact
3.Operating Current:0.5A
4.Differential Impedance:100Ω+/-10Ω
5.DWV:300 V AC
6.Insulation Resistance:1000MΩmin
7.Contact Resistance:70mΩmax

Materials

1.Cage:Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel
2.Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lee-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

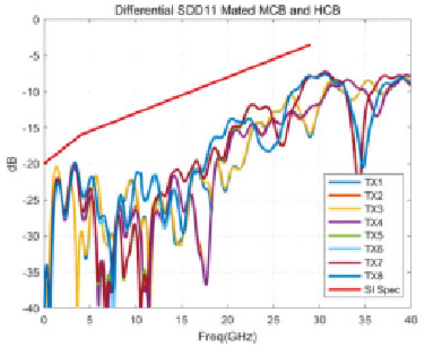
1.Operating Temperature:-40℃ to +85℃
2.Storage Temperature:-55℃ to +105℃

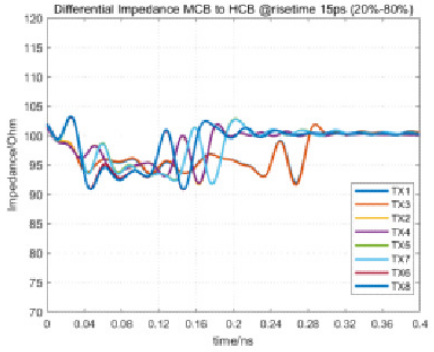
Options

1.Dust Cover
2.Light Pipe(Inner Light Pipes or Outer Light Pipes)
3.Heat Sink
4.EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging

1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover





Single & Rows CFP2 Cage/Connector

MATERIAL

1.Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic Contacts Base 2.Material: Phosphor Bronze
3.Plating Solder Tails: Matte tin
4.Plating Mating Area: Gold
5.Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE

1.Durability: 200 mating cycles
Mating Force: 80 N max.
2.Contact Normal Force: 30 grams
3.PCB Thickness (Cage): 3.00 mm (0.118 in.) Unmating Force (Cage): 50 N

ELECTRICAL PERFORMANCE

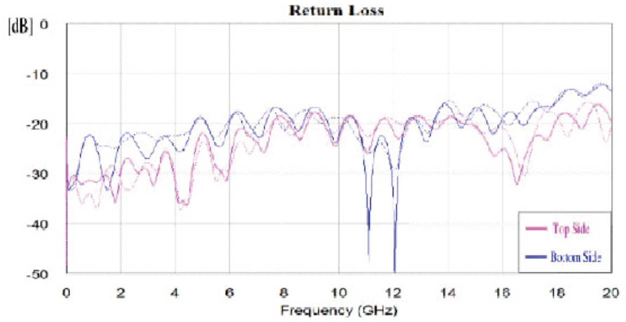
1.Operating Voltage: 3.3 V DC per contact
(Class 4 or lower) / 1.25A maximum (Class 5 and 6)
2.Operating Current (per signal pin): 0.5A maximum

ENVIRONMENTAL

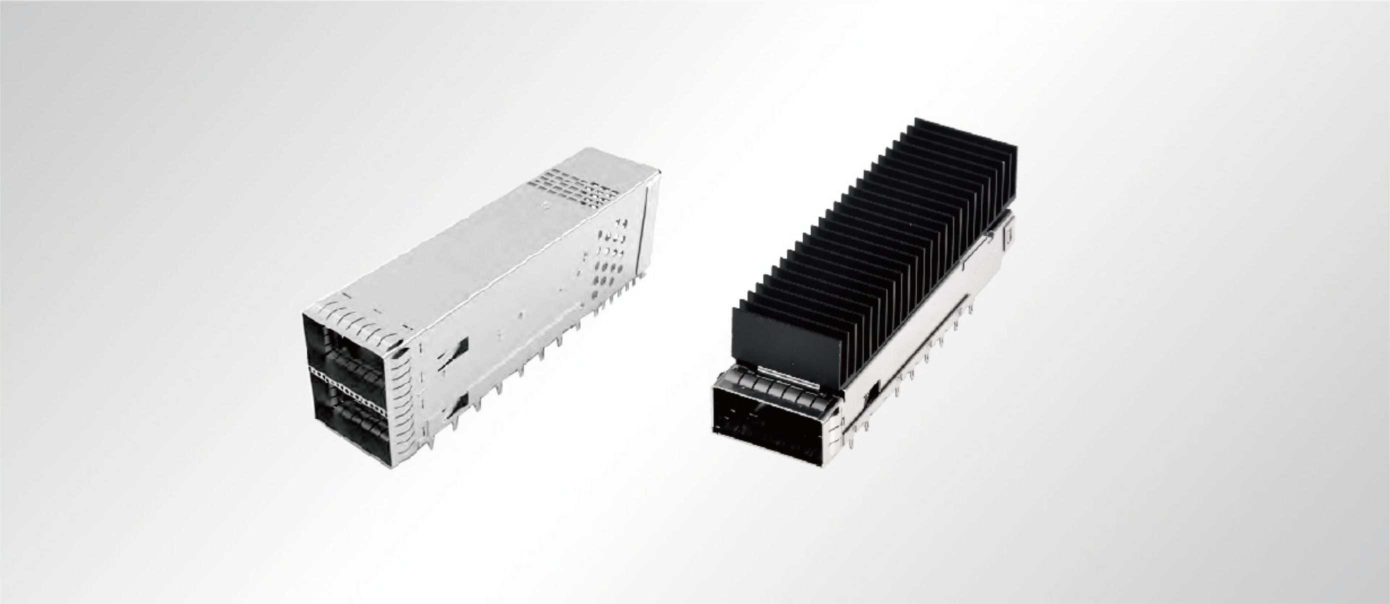
1.Operating and (Storage) Temperature: -40°C to +85°C
2.RoHS

TOOLING INFORMATION

Configurations: 1X1



Single & Stacked OSFP Connector



MATERIAL

1. Housing: Black color, Glass reinforced, Lead Free
   Solder Reflow Process Compatible Thermo Plastic
2. Contacts Base Material: Phosphor Bronze
   Plating Solder Tails: Matte tin over Nickel
3. Plating Mating Area: Gold
4. Resonance Dampening Feature: Carbon fibre reinforced

MECHANICAL PERFORMANCE

1.Durability: 250 mating cycles
2.Mating Force: 40 N max.
3.Unmating Force: 40 N max.
4.Contact Normal Force: 40 grams min.

ELECTRICAL PERFORMANCE

1. Operating Voltage: 30 VDC per contact
2. Operating Current:
3. 0.5 A per signal contact
4. 1.5 A per low speed power contact
5. Differential Impedance: 100Ω +/- 10Ω

ENVIRONMENTAL

1. Operating and (Storage) Temperature: -20° to +85° C
2. RoHS & Halogen-Free

TOOLING INFORMATION

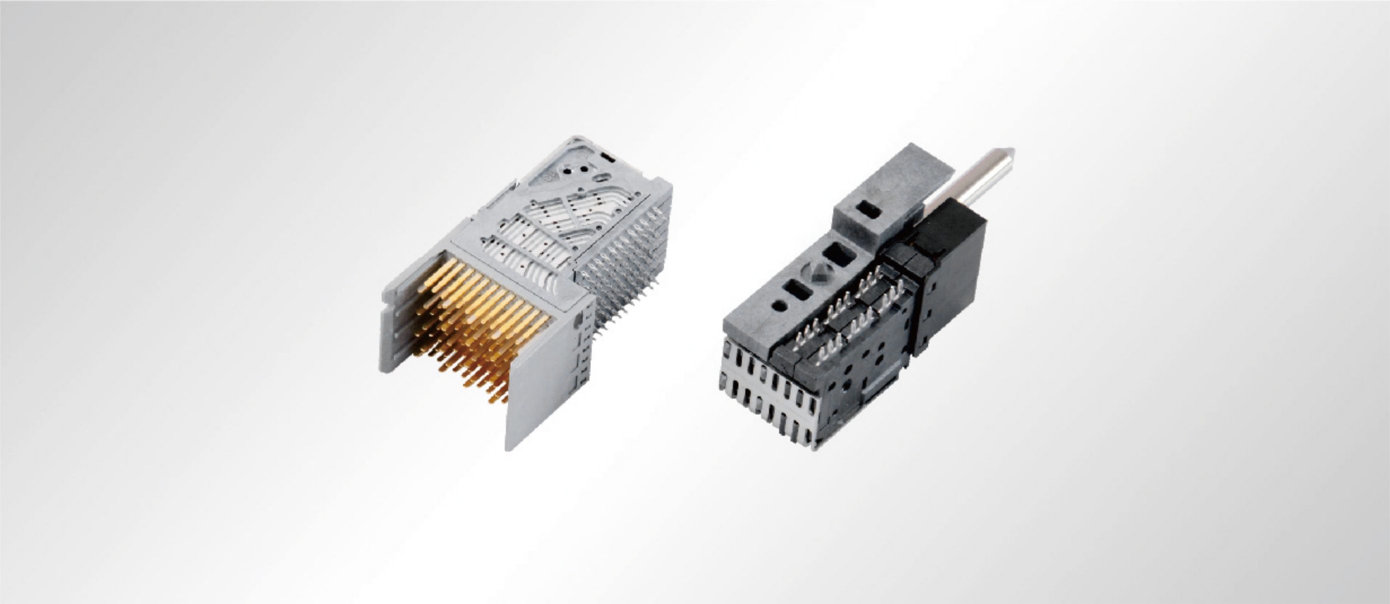
1. Configurations:

(1) 1x1
(2) 2x1

PACKAGING

Tape and Reel or Tray

High Speed Backplane Connector



High Speed Backplane Connectors

Material

Signal Contact: Copper Alloy
Ground Contact: Copper Alloy
Housing: Liquid Crystal Polymer UL 94V-0
Plating: 30" Ni
Compliant Pin Plating: RoHS

Feature

Temperature Range: --65℃ to 90℃
Current Rating: 0.5A/contact @<30℃
Durability: 200 cycles
Voltage: 560 VAC
Operating Voltage: 250 VAC

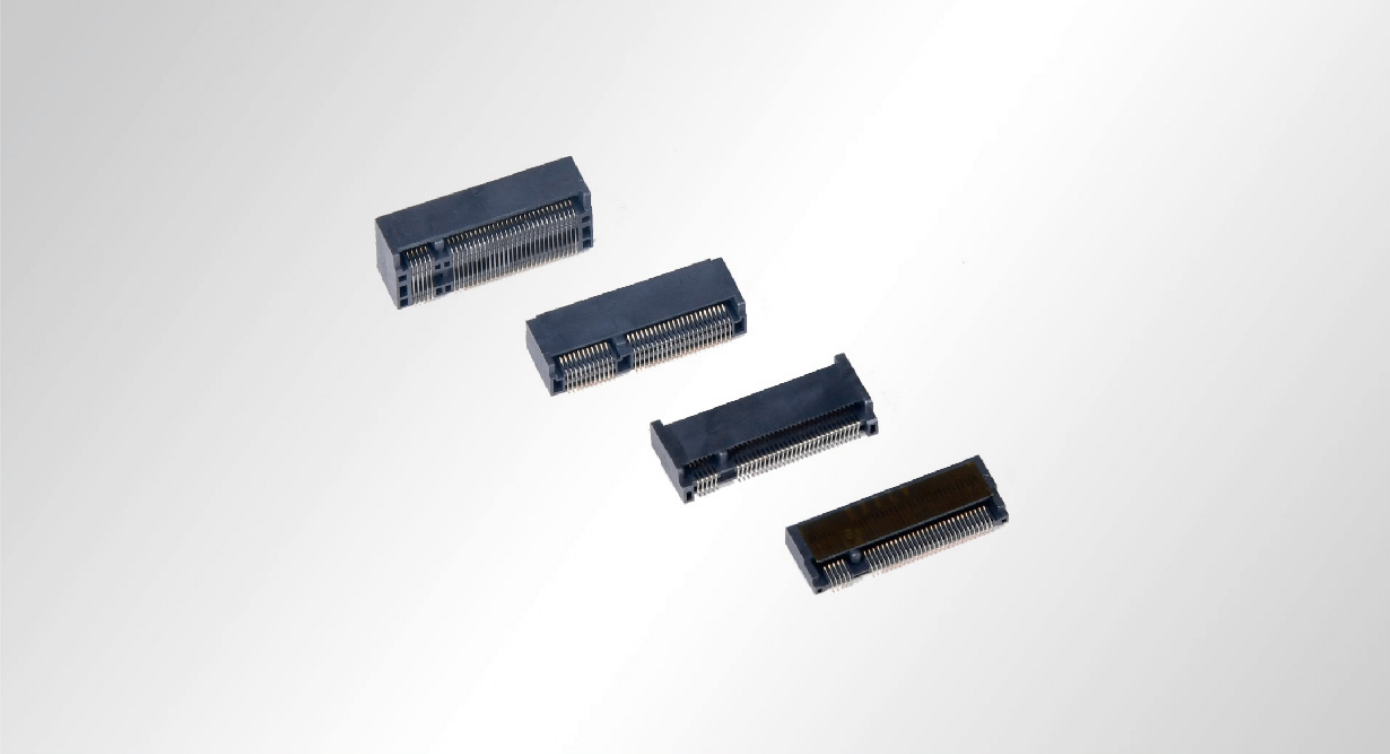
Signal

Impedance: Differential @100 ohms ±10%
Crosstalk: Multi-pair Differential crosstalk 2.1% @50ps
Insertion Loss: -2dB @10GHz

Specification

10+ Gbps performance
100 ohm impedance
Max 66 differential pairs/inch
50 Gbps @IB HDR
56.1 Gbps @128GFC

Card Edge Product Family: M.2



MECHANICAL PERFORMANCE

1.Insertion force (module to connector): 25N max

2.Terminal retention force: 100gf min.

3.Durability: 25cycles

ELECTRICAL PERFORMANCE

1.Low level contact resistance: 55mΩ initial, △20mΩ

2.Insulation resistance: 100MΩ min.

3.Dielectric withstanding voltage: 300VAC.

4.Current rating: 0.5A/pin De-rate

ENVIRONMENTAL

1.Flammability: UL 94 V-0

2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.

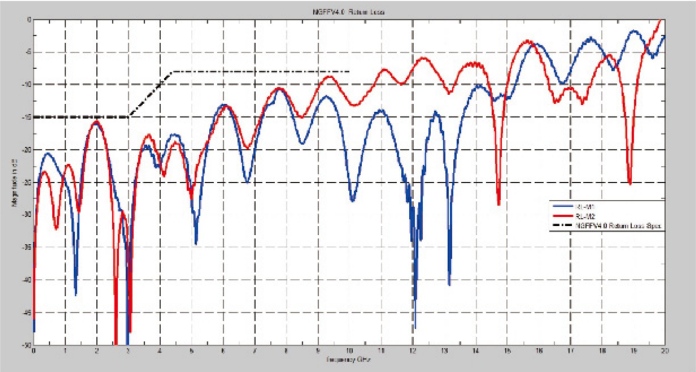
3.Compliant with RoHS directive 2011/65/EU

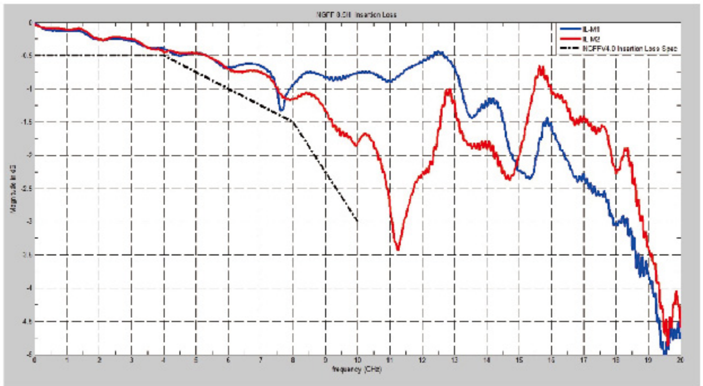
4.Operating Temperature: -40℃ to + 80℃

SPECIFICATION

1.PCI Express M.2 SPEC:

2.DELEC PRODUCT SPEC: DE-PS-0024





Internal High speed IO Series: MCIO/4X/8X16X

MECHANICAL PERFORMANCE

1.Insertion force: 1.15N/Pair max.

2.Unmating force: 0.10N/Pair min.

3.Terminal retention force: 200gf min.

ELECTRICAL PERFORMANCE

1.Low level contact resistance: 20mΩ initial, △10mΩ

2.Insulation resistance: 1000MΩ min.

3.Dielectric withstanding voltage: 300VAC.

4.Current rating: 1.0A/pin De-rate

ENVIRONMENTAL

1.Flammability: UL 94 V-0

2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.

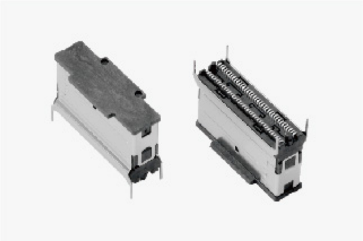
3.Compliant with RoHS directive 2011/65/EU

4.Operating Temperature: -55℃ to + 85℃

SPECIFICATION

1.JEDEC SPEC:
Industry specification SFF-TA-1016

2.DELEC PRODUCT SPEC:
DE-PS-0088



Card Edge Product Family: PCI Express5.0/X1/X4/X8/X16

MECHANICAL PERFORMANCE

1.Insertion force (module to connector): 1.15N/Pair max.
2.Unmating force: 0.15N/Pair min.
3.Terminal retention force: 200gf min.
4.Durability: 50cycles.

ELECTRICAL PERFORMANCE

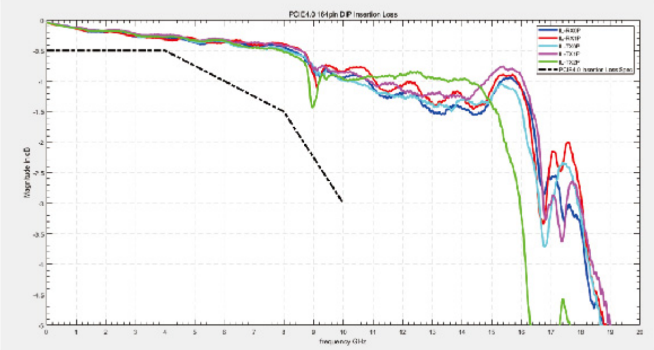
1.Low level contact resistance: 30mΩ initial, △10mΩ
2.Insulation resistance: 1000MΩ min.
3.Dielectric withstanding voltage: 500VAC.
4.Current rating: 1.0A/pin De-rate

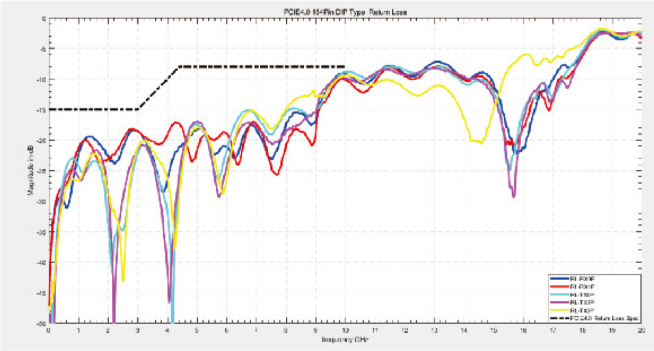
ENVIRONMENTAL

1.Flammability: UL 94 V-0
2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
3.Compliant with RoHS directive 2011/65/EU
4.Operating Temperature: -40°C to + 85°C

SPECIFICATION

1.PCI Express card electromechanical specification
2.DELEC product spec:
DE-PS-0088





Card Edge Product Family: SLIVER 224CKTS STRADDLE MOUNT

MECHANICAL PERFORMANCE

1.Insertion force (AIC to connector): 1.1N/pair max
2.Unmating force: 0.1N/pair min.
3.Durability: 25cycles.

ELECTRICAL PERFORMANCE

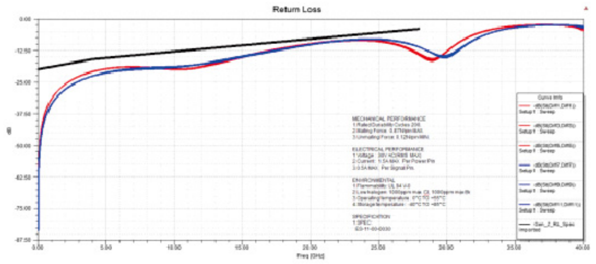
1.Low level contact resistance: 30mΩ initial, △15mΩ
2.Insulation resistance: 100MΩ min.
3.Dielectric withstanding voltage: 300VAC.
4.Current rating: 1.1A/pin De-rate

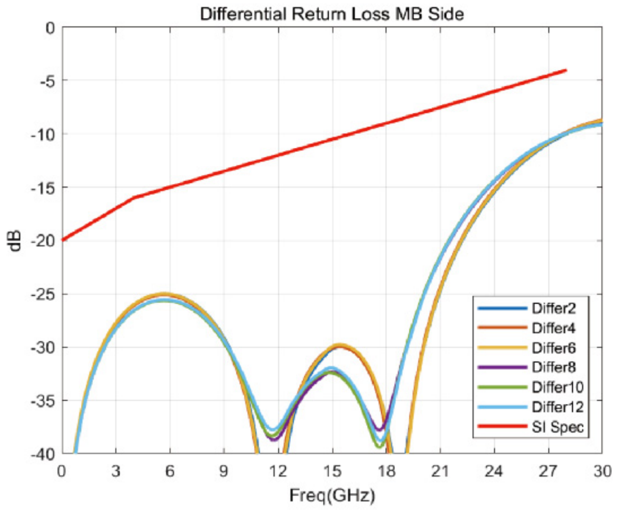
ENVIRONMENTAL

1.Flammability: UL 94 V-0
2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
3.Compliant with RoHS directive 2011/65/EU
4.Operating Temperature: -55°C to + 85°C
5.Thermal shock: 5 cycles between -55°C to +85°C
6.Temperature life: 105°C for 168 hours.

SPECIFICATION

1.SPEC:
SFF-TA-1002





U.3 Connector(SAS 3.0 7+15PIN/SAS 3.0/SAS 4.0/SAS 5.0)

MECHANICAL PERFORMANCE

1.Rated Durability Cycles 200.
2.Mating Force: 0.87N/pin MAX.
3.Unmating Force: 0.12N/pin MIN.

ELECTRICAL PERFORMANCE

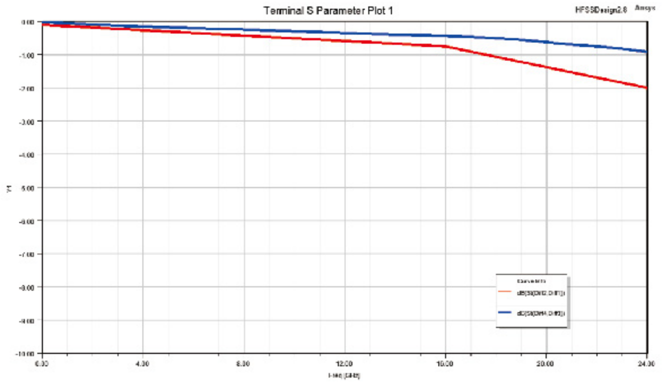
1.Voltage : 30V AC(RMS MAX)
2.Current : 1.5A MAX Per Power Pin
3.0.5A MAX Per Signal Pin.

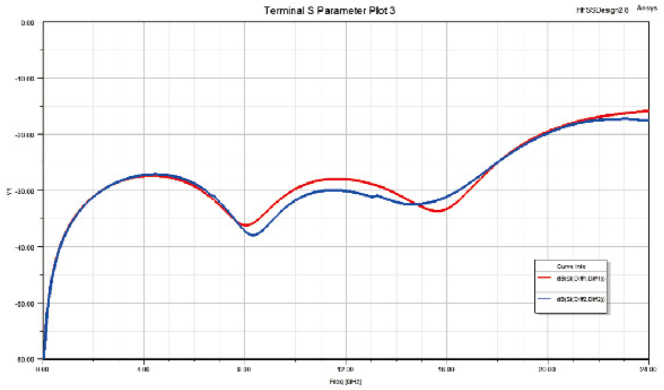
ENVIRONMENTAL

1.Flammability: UL 94 V-0
2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
3.Operating temperature : 0℃ TO +55℃
4.Storage temperature : -40℃ TO +85℃

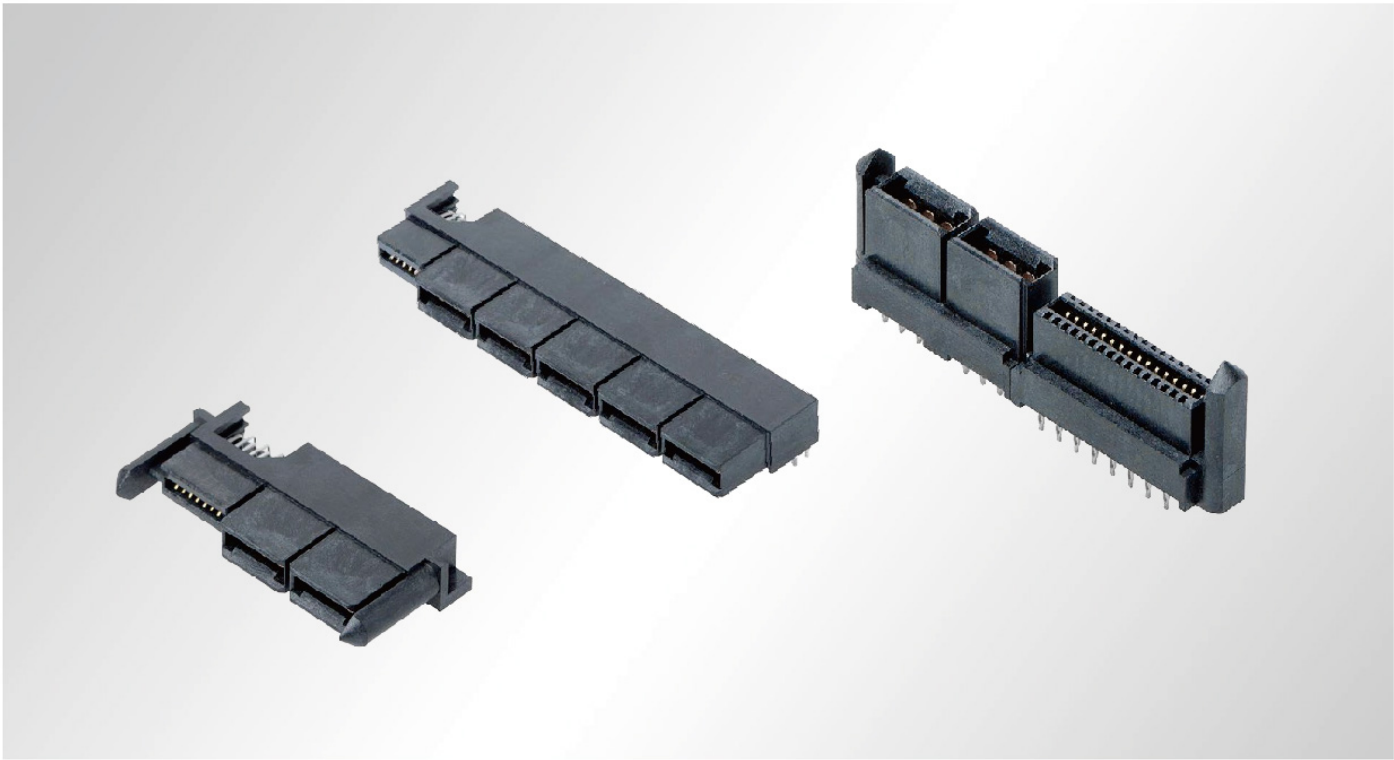
SPECIFICATION

1.SPEC:
ES-11-00-0030





EXTreme LPHPower Connectors/Hybrid Right-Angle Receptacles



MECHANICAL PERFORMANCE

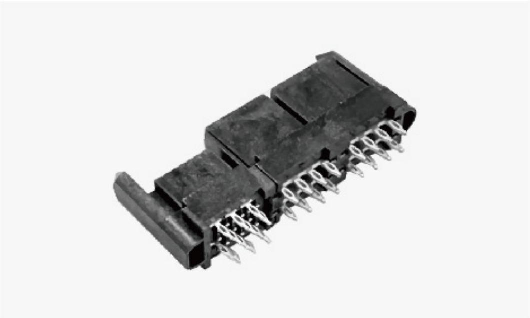
Mating Force (max. per circuit):
Power Contacts-6.87N (1.54 lb.
Signal Contacts- 1.08N (0.24 lb.)
Un-mating Force (min per circuit):
Power Contacts -1.47N (0.33 lb.)
Signal Contacts - 0.15N (0.03 lb.)
Durability: 250 cycles (receptacle and plug)

ELECTRICAL PERFORMANCE

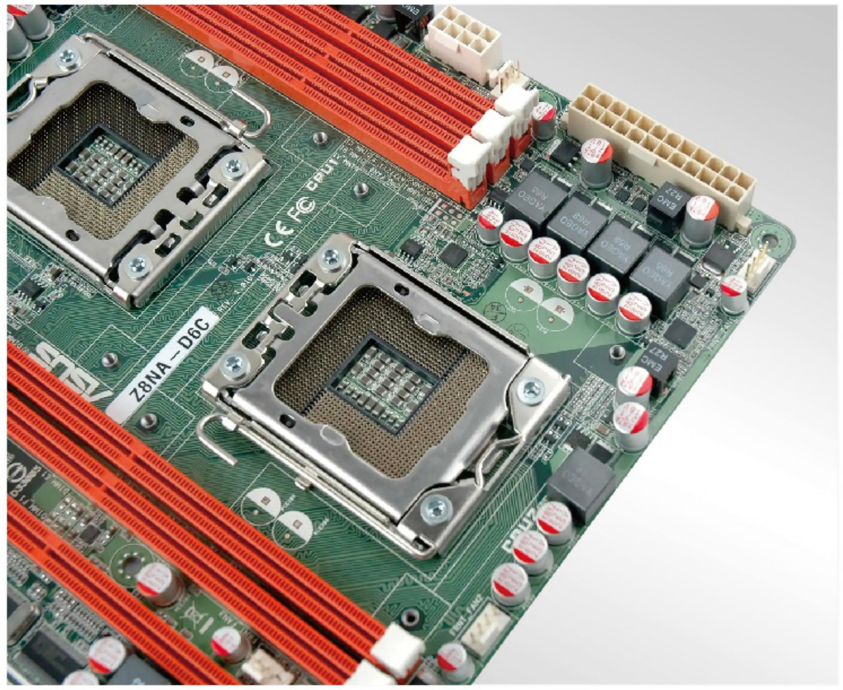
Voltage: 250V max.
Current (at 30'C temperature rise):
Power: 30.0A max.
Signal: 1.0A max.
Contact Resistance (per contact):
Min Max
Power(milliohms)-0.11 0.02
Sianal(milliohms) 0.35 0.47
Dielectric Withstanding Voltage: 1.500V
Insulation Resistance (Min.): 5.000 Megohms
Current interruption:
Power - 30.0A and 48V DCSignal - 1.0A at 30V

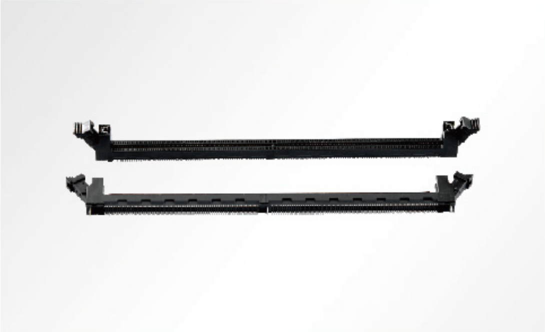
Physical

Housing: LCP
Contact:
Power Contacts -Copper(Cu) alloySiqnal Contacts-Copper (Cu) Alloy
Plating:
Contact Area-Select GoldSolder Tail Area - TinUnderplating-Nickel
Flammability Rating: UL 94V-0
Operating Temperature: -40 to +105℃



Card Edge Product Family: DDR DIMM/DDR SO DIMM





MECHANICAL PERFORMANCE

1.Insertion force (module to connector): 106.8N max

2.Terminal retention force: 300gf min.

3.Durability: 25cycles.

ELECTRICAL PERFORMANCE

1.Low level contact resistance: 10mΩ initial, △10mΩ

2.Insulation resistance: 1MΩ min.

3.Dielectric withstanding voltage: 250VAC.

4.Current rating: 0.75A/pin De-rate

ENVIRONMENTAL

1.Flammability: UL 94 V-0

2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.

3.Compliant with RoHS directive 2011/65/EU

4.Operating Temperature: -55°C to + 85°C

SPECIFICATION

1.JEDEC SPEC:

DDR4 288pin: SO-016 (DIP), SO-018(SMT)

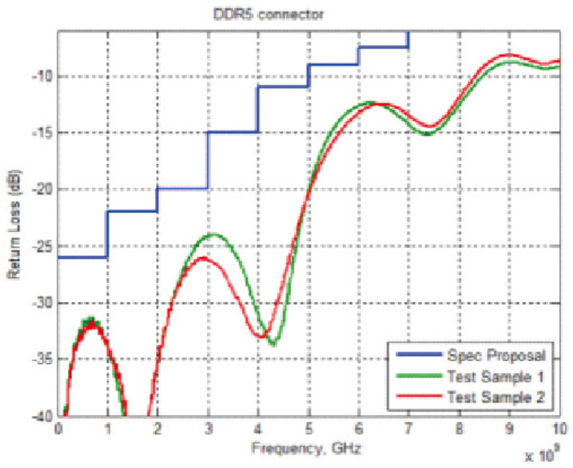
/ MO-309 (Module)

DDR5 288pin: SO-023 / MO-369

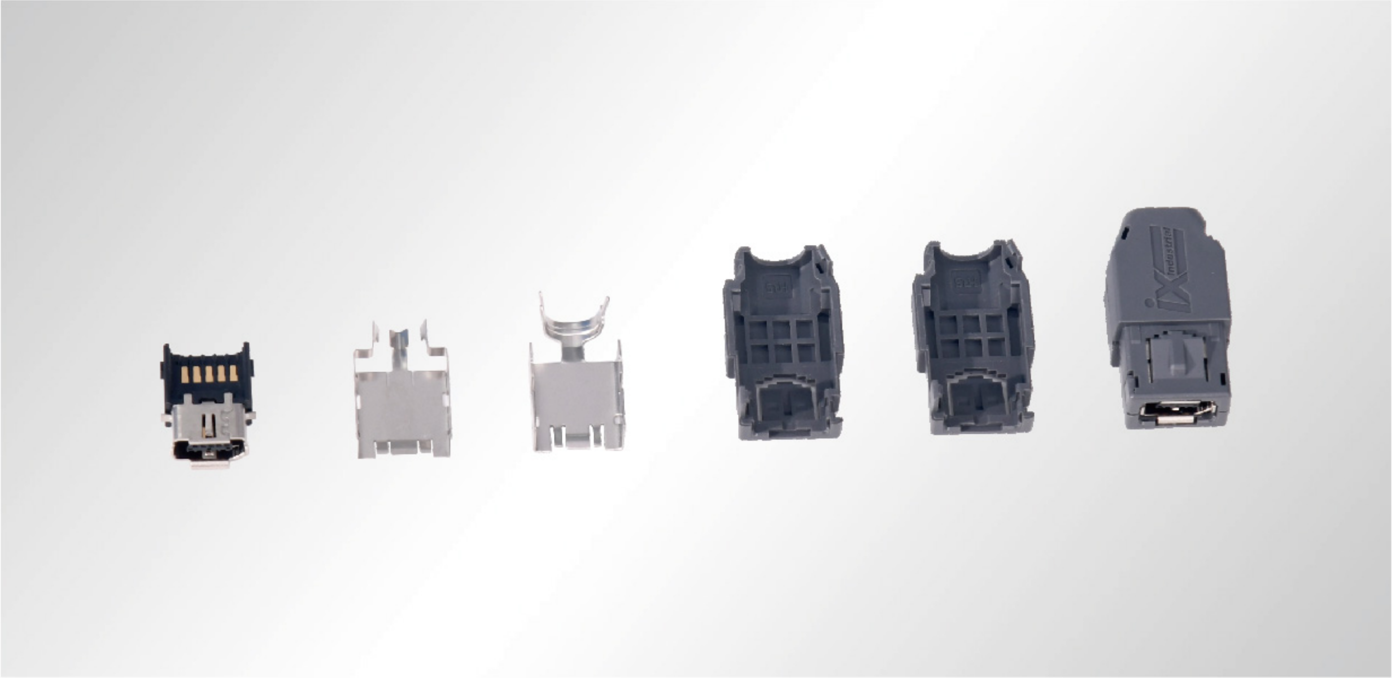
2.DELEC PRODUCT SPEC:

DDR4: DE-PS-0046

DDR5: DE-PS-0115



IX Series Connector (Industrial Transmission connector)



MATERIAL

1. RoHS COMPLIANT PER EU DIRECTIVE 2011/65/EU AND AMENDMENTS.
2. STAINLESS STEEL, MATTE TIN OVER NICKEL PLATED.
3. INSERTS: HIGH TEMPERATURE RESISTANT ENGINEERING THERMOPLASTIC, GLASS REINFORCED, UL94V-0.
4. CONTACTS: COPPER ALLOY PLATED WITH GOLD OR PALLADIUM-NICKEL (SEE ORDERING CODE)

   OVER 1.27µm (50µ") MINIMUM NICKEL ON THE MATING AREA AND MATTE TIN OVER

   NICKEL ON THE SMT TAILS. CODE 4 MATING AREA PLATING 1.27µm (50µ") GOLD

   OPTION CONFORMS TO ASTM B488, TYPE 2, CODE C, CLASS 1.25.

   MID-PLATE: STAINLESS-STEEL

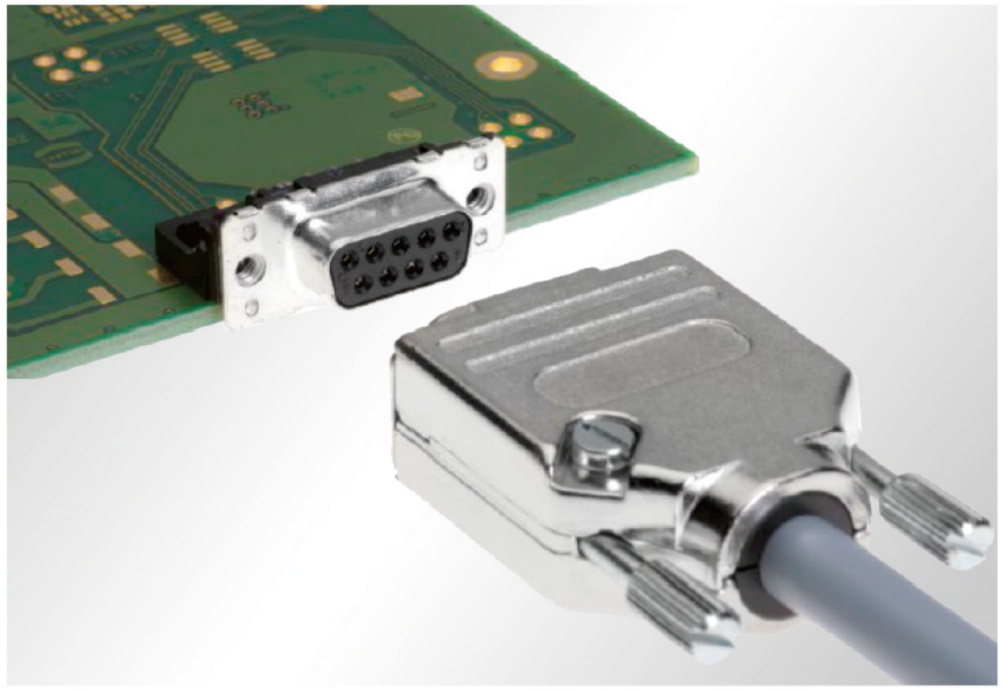
Specifications

1. CONNECTORS ARE PROVIDED IN TAPE & REEL PACKAGING FOR PICK & PLACE PROCESSING

   AND ARE SUITABLE FOR IR REFLOW SOLDERING OF PIN IN PASTE SHIELD TAILS AND SURFACE MOUNT CONTACT TAILS.
2. DESIGNED TO CONFORM TO REQUIREMENTS OF IEC 61076 PART 3-124 SPECIFICATION. THE A KEY FEATURE SHOWN IS INTENDED FOR USE WITH ETHERNET APPLICATIONS, EITHER 10/100 MBit/S OR 1 TO 10 GBit/S (CAT 5e, 6 & 6A).
3. CURRENT RATING:

   1.5 A PER POSITION (30° MAX TEMPERATURE RISE PER UL1977 & CSA C22.2 NO 182.3 STANDARDS) VOLTAGE RATING: 50V AC rms OR 60V DC
4. OPERATING TEMPERATURE -55° TO +105°C.
5. DIELECTRIC WITHSTANDING VOLTAGE: 500V DC
6. CONTACT RESISTANCE: 30 MILLIOHMS MAXIMUM.
7. INSULATION RESISTANCE: 500 MEGOHMS MINIMUM.
8. MATING & UNMATING FORCE: 25N (5.6 lbf) MAXIMUM.

D-SUB Series Connector



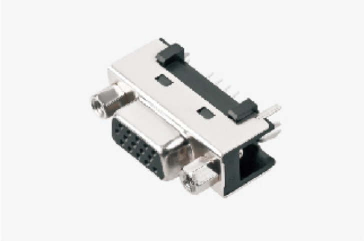
D-SUB Series

MATERIALS

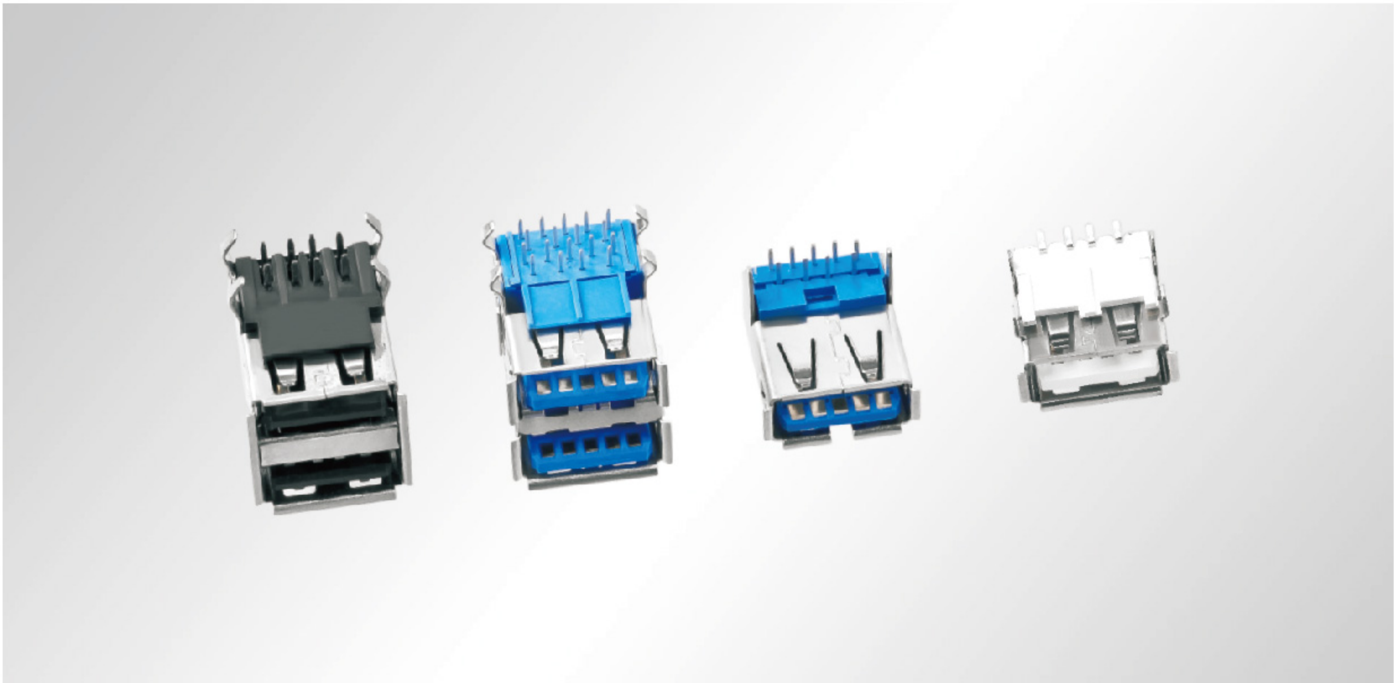
Insulator: high temperature thermoplastic, UL94V-0 Blue
Contact terminal: 30 u" Au plated on contact area
50u"min Matte Tin plated on solder area;
50u"min Nickel underplating over all.
Crust: SPCC, plated Ni

Specifications

1.Electrical requirements:
Current rating: 1A
Contact resistance: ≤30mΩ
Insulation resistance: ≥1000MΩ
Withstanding voltage: 500 Vr.m.s,1mA,60s
2.Mechnical requirements
Insertion force: ≤3.3 N/pin
Extraction force: ≥0.3 N/pin
Mechanical life: 200 cycles
3.Environment specification
Working temperature: -40℃~+100℃
Humidity: ≤93% at 40℃
4. Applicable standard: IEC60807
5. Storing:
Storing condition: temperature of -10℃~+40℃
below 80% relative humidity
6. To prevent the pollution of the environment product
info: In line with the European union RoHS



USB & HDMI Series Connector



HDMI Series

Material

1. Housing: LCP+30%G.F,UL94V-0,Black
2. Contact: Copper Alloy, Au And Sn Plated.
3. Shell: SK7, Ni Plated.

Specifications

Mating Force: 44.1N(4.5Kgf) max.
Unmating Force: 9.8N~39.2(1~4Kg).
Durability: 10,000 Cycles.

ELECTRICAL CHARACTERISTIC

Current Rating: 0.5A Max.
Voltage Rating: 40V AC Max.
Contact Resistance: 30m Ohm Max.
Insulation Resistance:
100M Ohm Min(unmated)
10M Ohm Min(mated)
Dielectric Withstanding Voltage:
500V AC Min

TEMPERATURE

Operating Temperature:
-40℃~+85℃
Storage Temperature:
-60℃~+105℃

USB Series

Material

1.Housing:Nylon,PBT(UL94-VO)Color:White,Black,
Blue orother colors are available
2.Contacts:Flat Pin:phosphor bronze plated with
Fu"'/3u""/6u"/15u"/30u*"Min hard gold plated over nickel.
3.Shielding:brass or spcc with nickel plated.

Specifications

Voltage Current Rating: USB(1A,30VAC),
HDMI(0.5A. 40VDC)
Insulation Resistance:1000MQ Min.
Contact Resistance:30mQ Ma
Dielectric Withstanding Voltage: 500V AC

USB2.0:Single USB2.0/Dual USB2.0(PTH solder type) availlable
Sing gle USB2.0(SMT solder type)available

USB3.0:Single USB3.0/Dual USB3.0(PTH solder type) available
Single USB3.0(SMT solder type)available"

Type C Connector

MATERIALS

1. HOUSING : LCP (UL 94V-0), BLACK.
2. TERMINAL : COPPER ALLOY,C18400 T=0.12
   GOLD Fu"/3u"/PLATED ON
   CONTACT AREA.
   GOLD FLASH PLATING ON SOLDER TAIL.
   NICKEL 50u" UNDERPLATED OVER ALL.
3. MID PLATE : STAINLESS STEEL. SUS301 T=0.15
4. SHELL : STAINLESS STEEL, SUS 301 T=0.30 NICKEL
   50u" MIN PLATING
5. EMI : STAINLESS STEEL, SUS 304 T=0.10 NICKEL
   50u" MIN PLATING

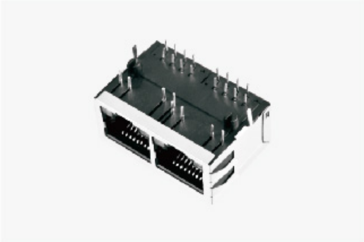
Specifications

1. CURRENT RATING :
   5.0A FOR Vbus PIN,
   1.25A FOR Vconn PIN,
   0.25A FOR OTHER PINS.
2. CONTACT RESISTANCE : 40mΩ.
3. INSULATION RESISTANCE : 100MΩ MIN.
4. DIELECTRIC WITHSTANDING VOLTAGE : 100 VAC MIN.
5. OPERATING TEMPERATURE : -40°C TO +85°C.
6. MATING FORCE : 5~20N.
7. UNMATING FORCE : 8~20N.
8. DURABILITY : 10,000 CYCLES.
9. RECOMMENDED PROCESS :
   THE PEAK TEMPERATURE ON THE BOARD SHALL
   MAINTAIN 260°C.
10. SALT SPRAY : 48 hour

RJ45 1XN Series Integrated Connector Modules

RJ45 1XN Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/5G/10G
Base-T RJ45 Connector



Material

1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port: 1X1/1X2/1X4
2.Position Number:8 Positions or 10 Positions available
3.Contact Number: 8 Contacts
4.Tab Up or Tab Down available.
5.Shielding: Non-Shielded/Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T Schematic available.
7.LED:Without LED/ With LED option (Differnet colors of LED option available)
8.1X1 port Tab up / SMT Type available.

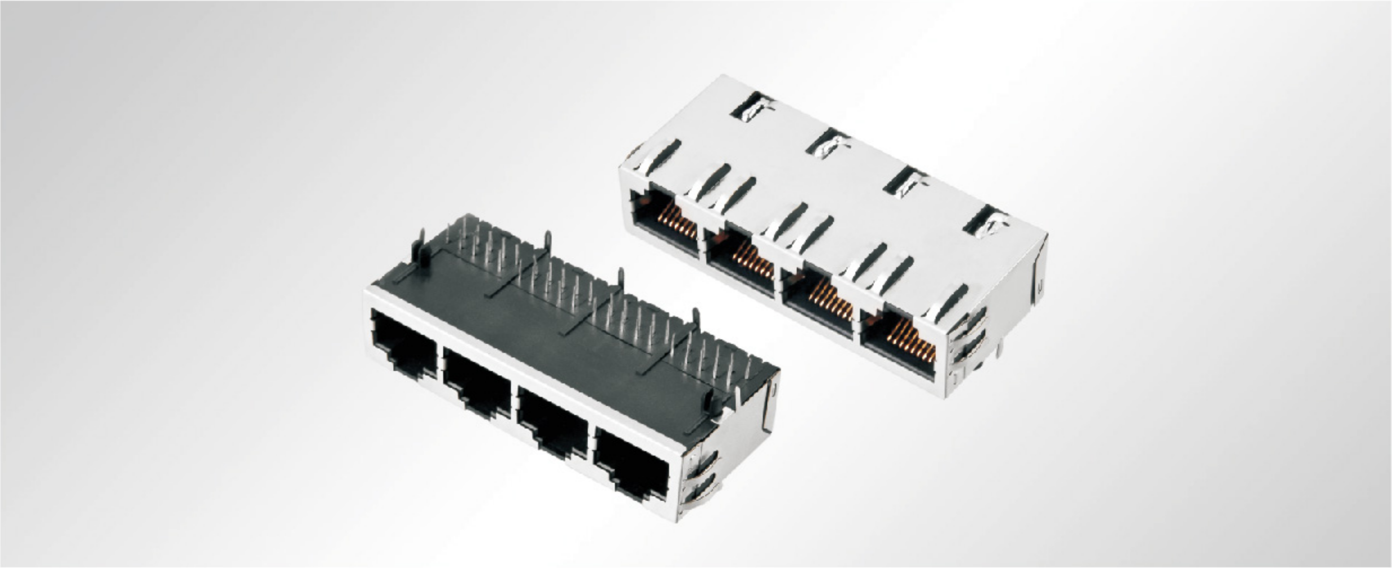
Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0°C to +70°C
Storage temperature:-40°C to +85°C

ELECTRICAL CHARACTERISTICS @ 25°C
10/100 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC Min.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz- 0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 1XN Series Integrated Connector Modules



RJ45 1XN Series

1XN PORT Tab Up /Tab Down 10/100/1000/2.5G/5G/10G
Base-T RJ45 Connector

Material
1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

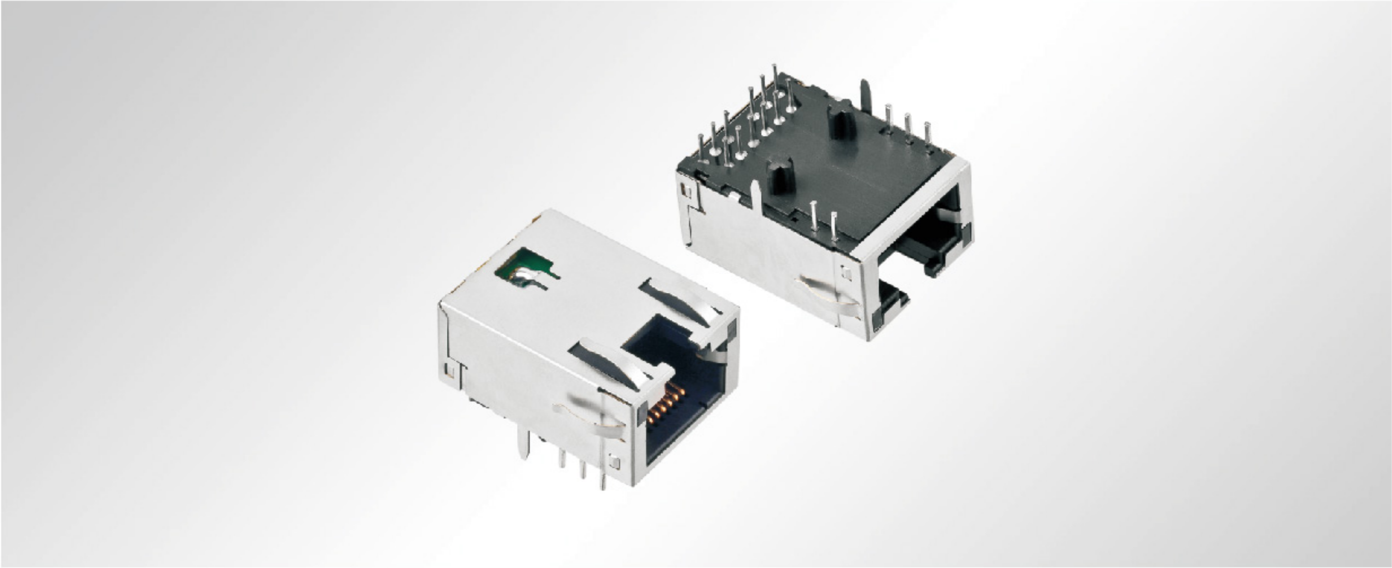
Specification Characteristic
1.Port: 1X1/1X2/1X4
2.Position Number:8 Positions or 10 Positions available
3.Contact Number: 8 Contacts
4.Tab Up available.
5.Shielding: Non-Shielded/Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T Schematic available.
7.LED:Without LED/ With LED option (Differnet colors of LED option available)

Feature
Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0℃ to +70℃
Storage temperature:-40℃ to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C
10/100 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

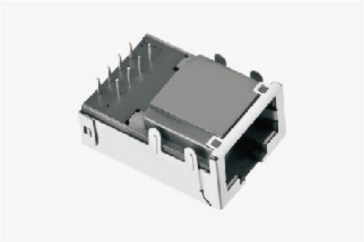
10/100/1000 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

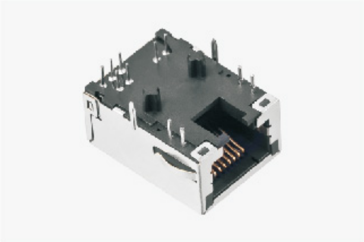
RJ45 1X1 Series Integrated Connector Modules



RJ45 1X1 Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/10G
Base-T RJ45 Connector





Material
1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

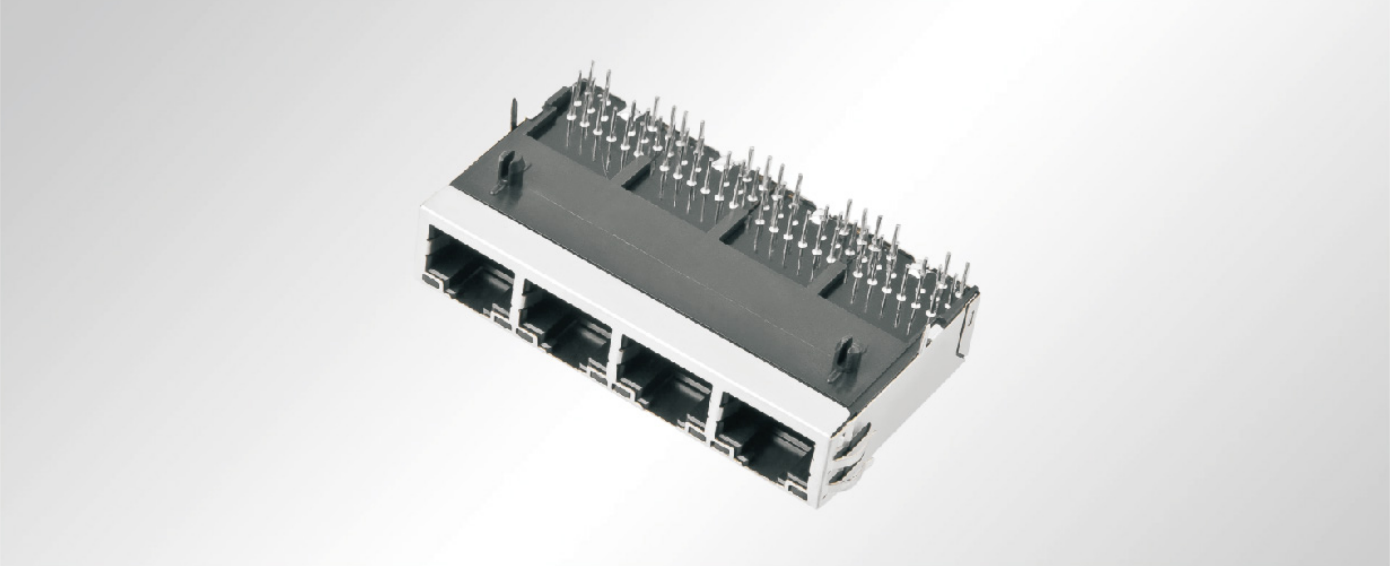
Specification Characteristic
1.Port: 1X1
2.Position Number:8 Positions or 12 Positions available
3.Contact Number: 8 Contacts
4.Tab Up or Tab Down available.
5.Shielding: Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T,10G Base-T Schematic available.
7.LED:Without LED/ With LED option (Differnet colors of LED option available)

Feature
Ultra low profile design
Shielded RJ45 connector with integrated 10/100BASE-T or 10/100/100BASE-T or 10GBASE-T Ethernet
Complies with IEEE802.3/IEEE802.3an standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0℃ to +70℃
Storage temperature:-40℃to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C
10/100/1000 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10G BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
120uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-20MHz -0.8dB MAX.
50MHz -1.0dB MAX.
200MHz -1.2dB MAX.
400MHz -2.0dB MAX.
500MHz -3.0dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -22dB MIN.
40MHz-100MHz -20dB MIN.
100MHz-200MHz -18dB MIN.
200MHz-300MHz -15dB MIN.
300MHz-400MHz -10dB MIN.
400MHz-500MHz -8dB MIN.
CM to CM Rejection:
1MHz-500MHz -20dB MIN.
CM to DM Rejection:
1MHz-250MHz -30dB MIN.
250MHz-500MHz -22dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.
100MHz-500MHz -20dB MIN

RJ45 1XN Series Integrated Connector Modules



RJ45 1XN Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/5G/10G
Base-T RJ45 Connector
With POE/POE+/UPOE/POE++ Options

Material
1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic
1.Port: 1X1/1X2/1X4
2.Position Number:8 Positions or 10 Positions available
3.Contact Number: 8 Contacts
4.Tab Up or Tab Down available.
5.Shielding: Non-Shielded/Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T Schematic available.
7.LED:Without LED/ With LED option (Differnet colors of LED option available)

Feature
Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0℃ to +70℃
Storage temperature:-40℃ to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C
10/100 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 2XN Series Integrated Connector Modules

RJ45 2XN Series

Stacked Ports 10/100/1000/2.5G/5G/10G
Base-t RJ45 Modules
WIth POE/POE+/UPOE/POE++ Options

Material
1.Housing:Nylon,PBT(UL94-V0)
Color:Black
2.Contacts:Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Minhard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

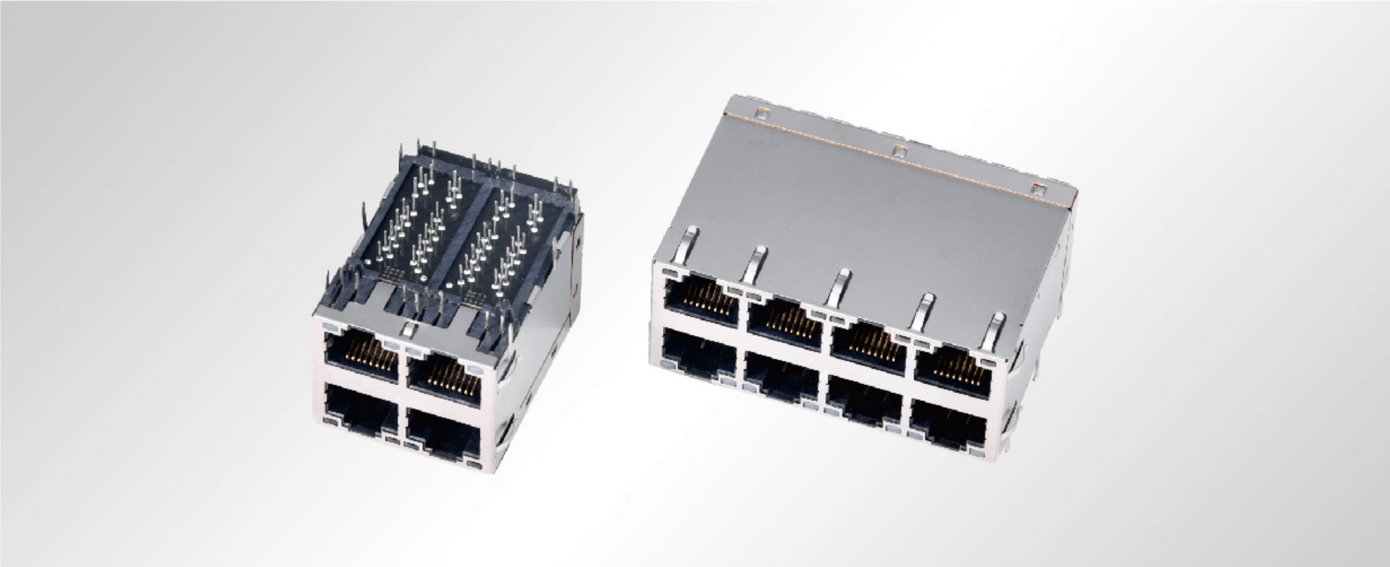
Specification Characteristic
1.Port: 2X1,2X2,2X4,2X6,2X8
2.Position Number:10 or 12 Positions available
3.Contact Number: 8 Contacts
4.Shielding:Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T ,POE , POE Plus Schematic available.
7.ESD/Surge Protection option.
8.LED:Without LED/ With Back LED option (Differnet colors of LED option available)

Feature
Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3af/at standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0℃ to +70℃
Storage temperature:-40℃ to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C
10/100 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product
Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN
Balanced DC Line current/Voltage rating(PSE Pins)
720mA Maximum @ 57V Continuous

RJ45 2XN Series Integrated Connector Modules



RJ45 2XN Series

Stacked Ports 10/100/1000/2.5G/5G/10G
Base-t RJ45 Modules
WIth POE/POE+/UPOE/POE++ Options

Material

1.Housing:Nylon,PBT(UL94-V0)
Color:Black
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port:2X4,2X6,2X8
2.Position Number:12 Positions available
3.Contact Number: 8 Contacts
4.Shielding:Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T,POE , POE Plus Schematic available.
7.LED:Without LED/ With Front LED option (Differnet colors of LED option available)

Feature

Shielded RJ45 connector with integrated 10/100 POE/POE Plus Ethernet
Complies with IEEE802.3af/at standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0℃ to +70℃
Storage temperature:-40℃ to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C

10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.

Insertion Loss:

1MHz-100MHz	-1.1dB MAX.

Return Loss:(Load:100 ohms)

1MHz-30MHz	-18dB MIN.
30MHz-60MHz	-18+20Log(F/30)dB MIN
60MHz-80MHz	-12dB MIN.

CM to CM Rejection:

1MHz-100MHz	-30dB MIN.

CM to DM Rejection:

1MHz-100MHz	-35dB MIN.

Cross Talk:

1MHz-100MHz	-30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.

Insertion Loss:

100KHz-1MHz	-1.1dB MAX.
1MHz-65MHz	-0.8dB MAX.
65MHz-100MHz	-1.0dB MAX.
100MHz-125MHz	-1.2dB MAX.

Return Loss:(Load:100 ohms)

1MHz-40MHz	-18dB MIN.
40MHz-100MHz	-12+20Log(F/80)dB MIN

CM to CM Rejection:

1MHz-100MHz	-30dB MIN.

CM to DM Rejection:

1MHz-100MHz	-35dB MIN.

Cross Talk:

1MHz-40MHz	-30dB MIN.
40MHz-100MHz	-33+20Log(F/50)dB MIN

RJ45 integrated connector with USB2.0/3.0 combo modules

RJ45+USB & RJ45 Vertical Serise

RJ45+USB2.0/3.0 & 10/10/1000/2.5G
Base-T Connector

Material

1.Housing:Nylon,PBT(UL94-V0)
2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port: 1X1
4.DE68 Vertical 180 Degree type design/ DE67 RJ45 with USB Combination
5.Shielding:Shielded with EMI Finger/Shielded without EMI Finger
6.Magnetics:10/100 Base-T, 10/100/1000 Base-T Schematic available.
7.LED:Without LED/ With LED option (Differnet colors of LED option available)
8.RJ45 with single USB2.0/ RJ45 with single USB3.0. available
RJ45 with dual USB3.0/ RJ45 with dual USB3.0. available

Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temper ature:0℃ to +70℃
Storage temperature:-40℃ to +85℃

ELECTRICAL CHARACTERISTICS @ 25°C

10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.

Insertion Loss:

1MHz-100MHz	-1.1dB MAX.

Return Loss:(Load:100 ohms)

1MHz-30MHz	-18dB MIN.
30MHz-60MHz	-18+20Log(F/30)dB MIN
60MHz-80MHz	-12dB MIN.

CM to CM Rejection:

1MHz-100MHz	-30dB MIN.

CM to DM Rejection:

1MHz-100MHz	-35dB MIN.

Cross Talk:

1MHz-100MHz	-30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Iput to Output isolation 1500Vrms/2250VDC.

Insertion Loss:

100KHz-1MHz	-1.1dB MAX.
1MHz-65MHz	-0.8dB MAX.
65MHz-100MHz	-1.0dB MAX.
100MHz-125MHz	-1.2dB MAX.

Return Loss:(Load:100 ohms)

1MHz-40MHz	-18dB MIN.
40MHz-100MHz	-12+20Log(F/80)dB MIN

CM to CM Rejection:

1MHz-100MHz	-30dB MIN.

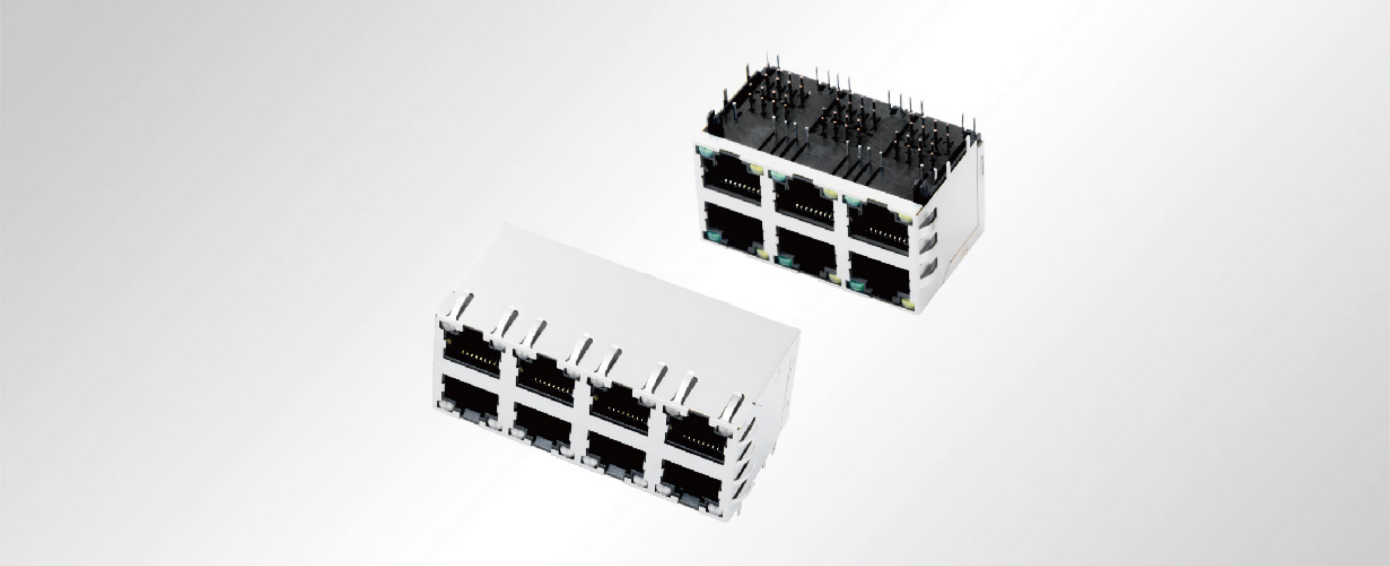
CM to DM Rejection:

1MHz-100MHz	-35dB MIN.

Cross Talk:

1MHz-40MHz	-30dB MIN.
40MHz-100MHz	-33+20Log(F/50)dB MIN

RJ45 2XN Module Jack Without Magnetics Connector



RJ45 2XN Series

RJ 45 Module Jack Without Magnetics

Material

1.Housing:Nylon,PBT(UL94-V0)Color:Black, Gray or other colors available.
2.Contacts:
  Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/ 3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
  Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port: 2X1,2X2,2X4,2X6,2X8
2.Position Number:8 Positions available
3.Contact Number: 8 Contacts
4.Shielding:Shielded with EMI Finger/Shielded without EMI Finger
5.LED:Without LED/ With LED option (Differnet colors of LED option available)

Electrical

1.Current Rating:1.5Amps per contact
2.Voltage Rating: 125Volts AC
3.Contact Resistance:30 miliohms Max
4.Insulation resistance:500Megohms Min @ 500VDC.
5.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

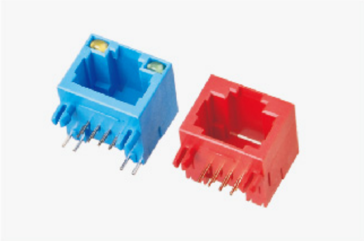
Feature

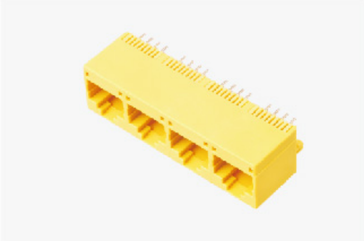
Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature:-40℃ to +85℃
Storage temperature:-40℃ to +85℃

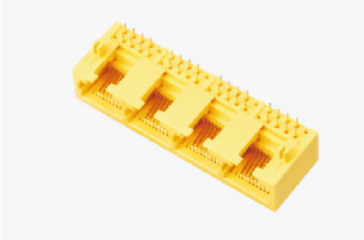
RJ45 1XN Module Jack Without Magnetics Connector

RJ45 1XN Series

RJ45 Module Jack Without Magnetics







Material

1.Housing:Nylon,PBT(UL94-V0)
  Color:Black,Gray or other colors available.
2.Contacts:
  Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/ 3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
  Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port: 1X1,1X2,1X4,1X8
2.Position Number:8 Positions available
3.Contact Number: 8 Contacts
4.Shielding:Withour Shield/Shielded with EMI Finger/ Shielded without EMI Finger
5.LED:Without LED/ With LED option (Differnet colors of LED option available)

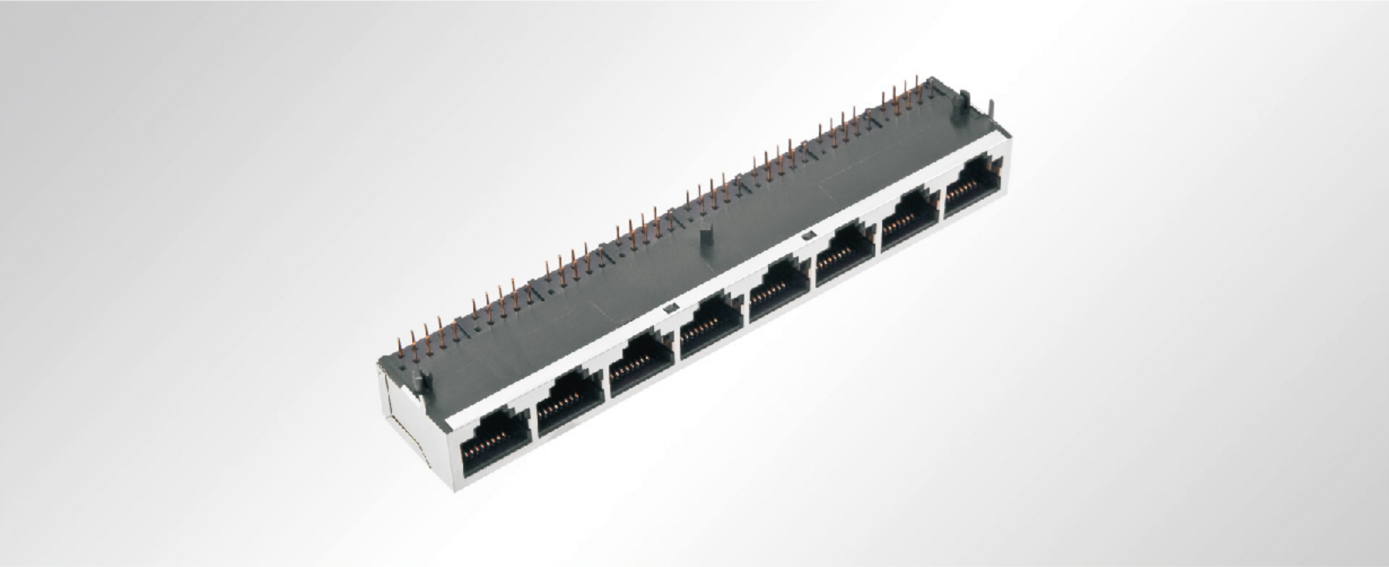
Electrical

1.Current Rating:1.5Amps per contact
2.Voltage Rating: 125Volts AC
3.Contact Resistance:30 miliohms Max
3.Insulation resistance:500Megohms Min @ 500VDC.
4.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

Feature

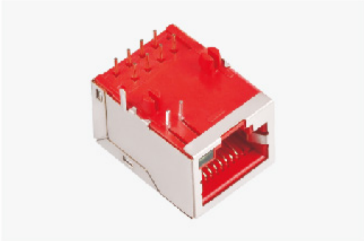
Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature:-40℃ to +85℃
Storage temperature:-40℃ to +85℃

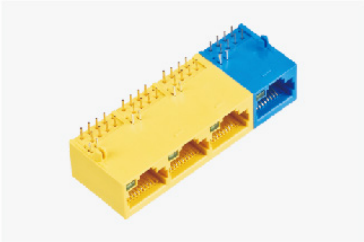
RJ45 1XN Module Jack Without Magnetics Connector



RJ45 1XN Series

RJ 45 Module Jack Without Magnetics





Material

1.Housing:Nylon,PBT(UL94-V0)
Color:Black,Gray or other colors available.
2.Contacts:
Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/ 3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

1.Port: 1X1,1X2,1X5,1X6,1X8
2.Position Number:8 Positions/10 Positions available
3.Contact Number: 8 Contacts /10 Contacts
4.Shielding:without Shield/Shielded with EMI Finger/Shielded without EMI Finger
5.LED:Without LED/ With LED option (Differnet colors of LED option available)

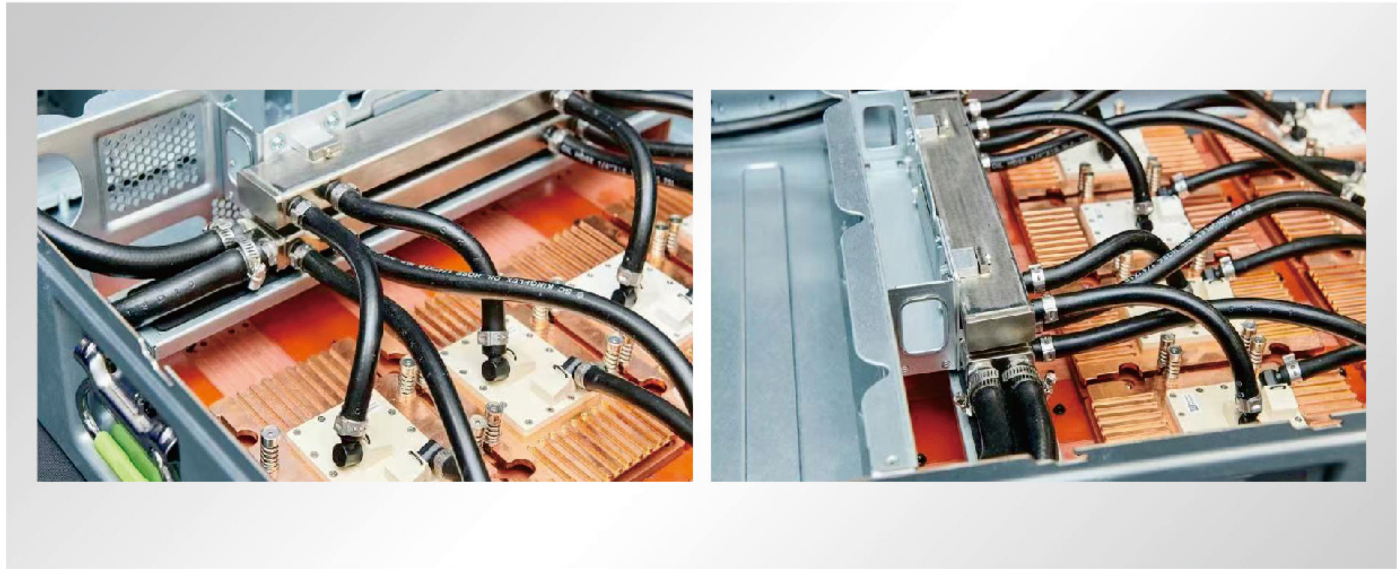
Electrical

1.Current Rating:1.5Amps per contact
2.Voltage Rating: 125Volts AC
3.Contact Resistance:30 miliohms Max
4.Insulation resistance:500Megohms Min @ 500VDC.
5.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

Feature:

Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature:-40℃ to +85℃
Storage temperature:-40℃ to +85℃

Radiator



Material:

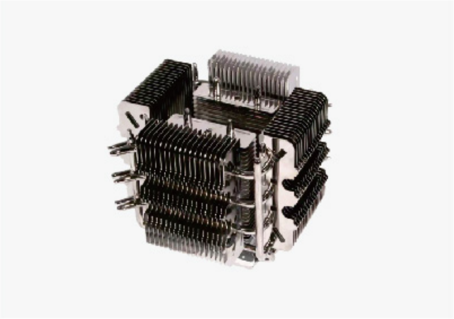
1.Sink:Copper heat pipe with aluminum fin
2.Pedestal:Copper
3.Plating : Ni plating
4.Contact Surface medium: Thermal paste or grease

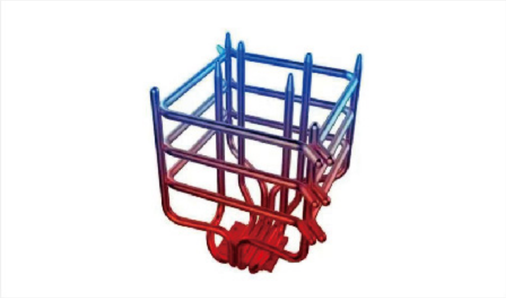
Electrical:

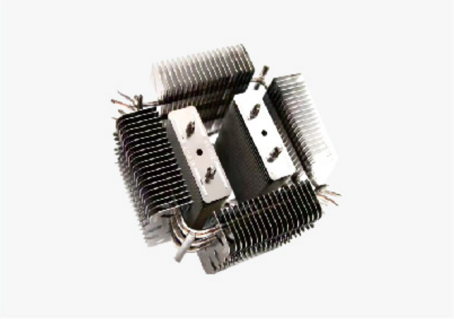
1.Voltage Rating: 12V
2.Current Rating:0.25-2.5Amps option
3. Fan speed:800-1500RPM
4. Rated Power:3W~30W option

Feature

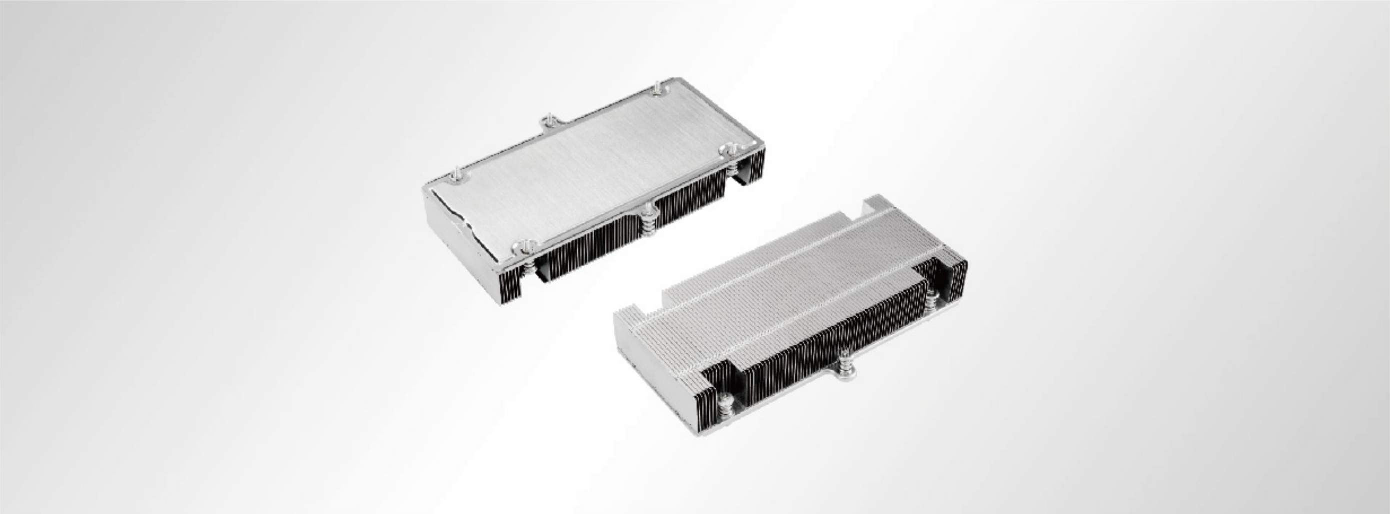
1. Anti-gravity pure copper heat pipe, fast conduction of chip heat
2. PWM intelligent speed regulation, high performance fan.
3. Innovative design and excellent quality
4. Multi-platform support
5.Operating Temperature:0℃ to 85℃
6.Storage Temperature:-40℃ to 105℃



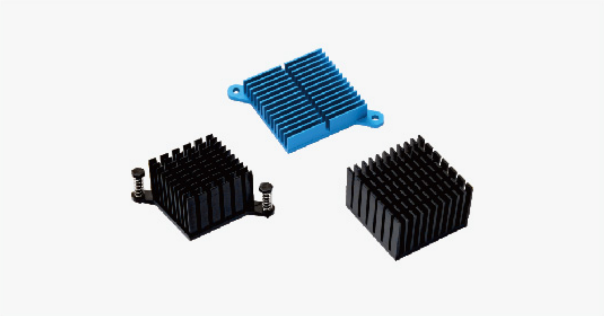


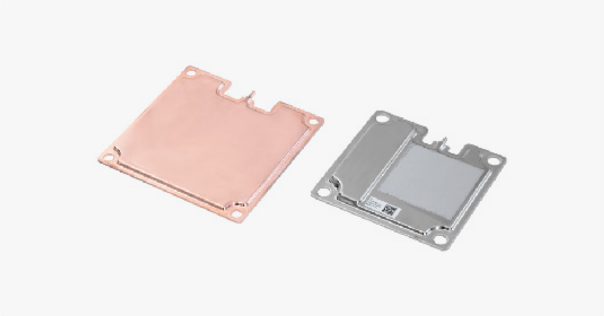


Vapor Chamber and Heat Sink



Vapor Chamber and Heat Sink





Material

Color: Silver, Copper and other color available
Pedestal: Copper
Sink: Aluminum and Copper
Plating: Ni 50" Min
Contact Surface Medium: Thermal Paste or Grease

Feature

Operating Temperature: 0 ℃ to 80 ℃
Storage Temperature: -40 ℃ to 130 ℃
Pressure Resistance: 3.0kg/cm^2
Thermal Shock: -40℃ to 100℃ 500 time
Life Time: 10 years

Specifications

Qmax: 350 W
Min Heat Resistance: 0.152 K/W
Sink Height: 1U
Sink Thickness: 0.45mm
Pedestal Thickness: 3.1mm
Pedestal Area: 144 cm^2
Flatness: <50μm